



SOT782-1

plastic thermal enhanced very thin small outline package; no leads; 8 terminals; 0.65 mm pitch, 3 mm x 3 mm x 0.85 mm body

6 December 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON8
Package type industry code	HVSON8
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-229
Mounting method type	S (surface mount)
Issue date	28-08-2009
Manufacturer package code	98ASA1366D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	0.8	0.85	1	mm
package height	-	0.82	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	8	-	



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2 Package outline

HVSON8: plastic thermal enhanced very thin small outline package; no leads;
8 terminals; body 3 x 3 x 0.85 mm

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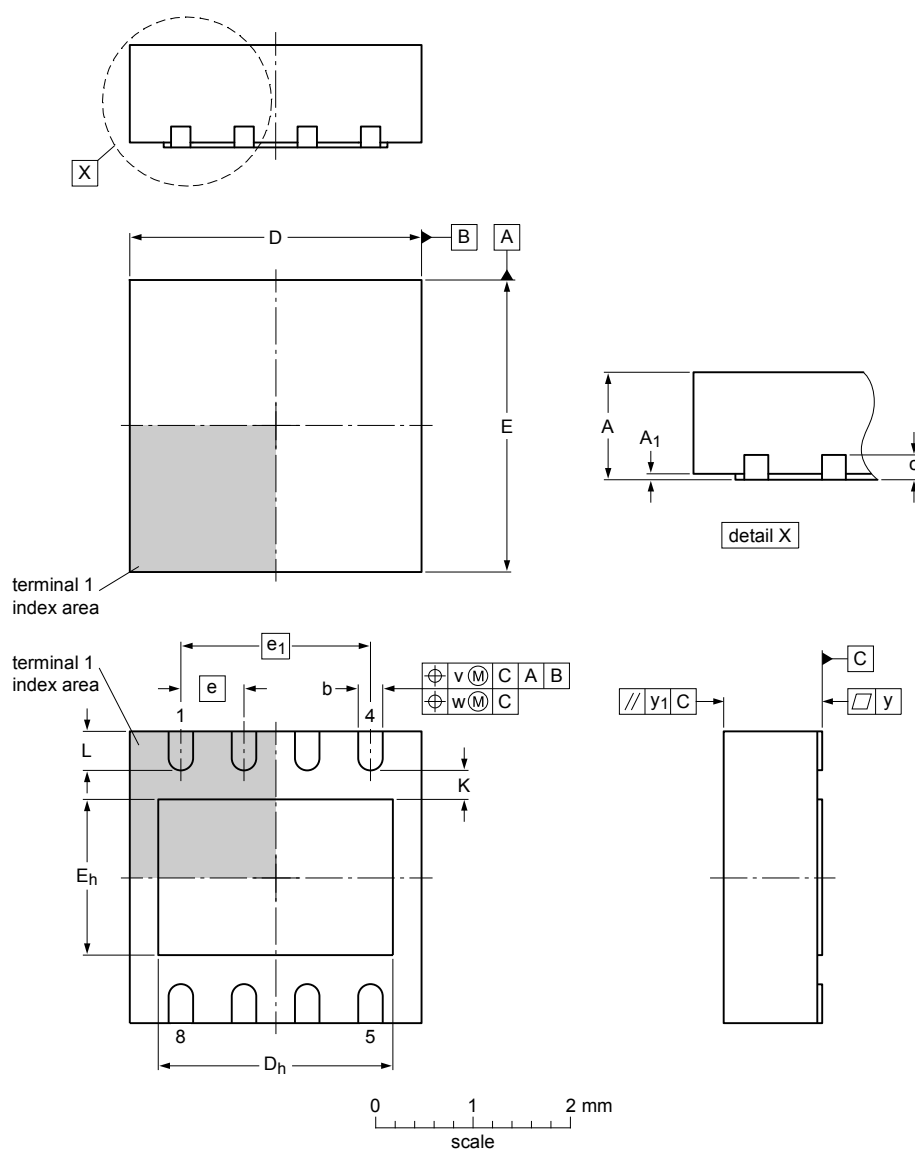


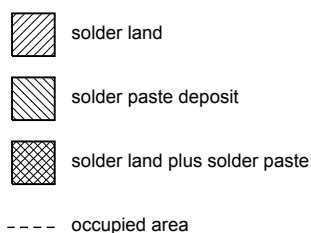
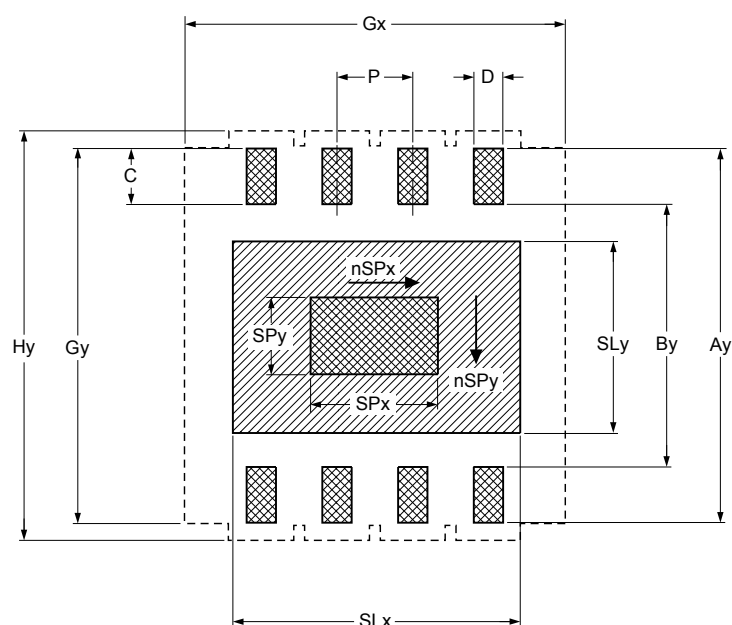
Figure 1. Package outline HVSON8 (SOT782-1)

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3 Soldering

Footprint information for reflow soldering of HVSON8 package

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DIMENSIONS in mm

P	Ay	By	C	D	SLx	SLy	SPx	SPy	Gx	Gy	Hy
0.65	3.25	2.2	0.525	0.3	2.45	1.65	1.1	0.65	3.25	3.25	3.5

nSPx	nSPy
1	1

Issue date	12-02-09 12-02-28
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Figure 2. Reflow soldering footprint for HVSON8 (SOT782-1)

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4 Legal information

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